

Material Content Data Sheet

RoHS

Sales Product Name	IPD65R660CFD	**Issued**	31. March 2021
MA#	MA001042652		
Package	PG-TO252-3-341	**Weight***	382.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.294	0.86	0.86	8615	8615
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		180	
	non noble metal	iron	7439-89-6	0.229	0.06		600	
	non noble metal	copper	7440-50-8	228.946	59.89	59.97	598814	599594
wire	non noble metal	aluminium	7429-90-5	0.468	0.12	0.12	1223	1223
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.721	0.45		4501	
	plastics	brominated resin	-	1.844	0.48		4822	
	organic material	carbon black	1333-86-4	1.967	0.51		5143	
	plastics	epoxy resin	-	16.592	4.34		43398	
	inorganic material	silicondioxide	60676-86-0	100.784	26.36	32.14	263602	321466
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9782	9782
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1331	1331
solder	non noble metal	tin	7440-31-5	0.059	0.02		155	
	noble metal	silver	7440-22-4	0.074	0.02		194	
	non noble metal	lead	7439-92-1	2.835	0.74	0.78	7416	7765
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019			50	
	non noble metal	copper	7440-50-8	19.177	5.02	5.02	50159	50224
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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